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Description

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(WO/2003/087230) THERMOSETTING RESIN COMPOSITION AND PREPREG AND LAMINATED SHEET USING THE SAME

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Claims

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Title: THERMOSETTING RESIN COMPOSITION AND PREPREG AND LAMINATED SHEET USING THE SAME

Abstract: A thermosetting resin composition, characterized in that it comprises (1) a metal salt of a di-

substituted phosphinic acid and (2) a resin exhibiting a relative dielectric constant at a frequency of 1

GHz or more of 2.9 or less; and a prepreg and a laminated sheet using the resin composition.

Designated AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, States:

DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

African Regional Intellectual Property Org. (ARIPO) (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG,

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